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(54) **TSV-TYPE EMBEDDED MULTI-DIE INTERCONNECT BRIDGE ENABLING WITH THERMAL COMPRESSION NON-CONDUCTIVE FILM (TC-NCF) PROCESS**

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(57) **ABSTRACT**

Embodiments disclosed herein include an electronic package. In an embodiment, the electronic package comprises a package substrate, and an opening in the package substrate. In an embodiment, a plurality of first pads are provided at a bottom of the opening, and a bridge die is in the opening. In an embodiment, the bridge die comprises a plurality of second pads that are coupled to the first pads by solder. In an embodiment, a non-conductive film (NCF) is around the solder between the first pads and the second pads.